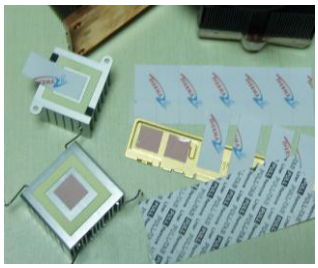
TIC™800P Series Low Melting Point Thermal Interface Materials

TIC™800P Series is low melting point thermal interface material. At 50℃, TIC™800P series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance.TIC™800P series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.

TIC™800P Series shows no thermal performance degradation after 1,000 hours@130℃,or after 500 cycles, from -25℃ to 125℃.The material softens and does not fully change state resulting in minimal migration (pump out)at operating temperatures.



Applications Include:

- 》High Frequency Microprocessors
- 》Notebook and Desktop PCs
- 》Computer Serves
- 》Memory Modules
- 》Cache Chips
- 》IGBTs

For Lowest Thermal Resistance :

- 》**0.021℃-in² /W** thermal resistance
- 》Naturally tacky at room temperature, no adhesive required
- 》No heat sink preheating required

Typical Properties of TIC™800P Series

Product Name	TIC™805P	TIC™808P	TIC™810P	Test Method
Color	Pink	Pink	Pink	Visual
Thickness	0.005" (0.126mm)	0.008" (0.203mm)	0.010" (0.254mm)	******
Thickness Tolerance	±0.0008" (±0.019mm)	±0.0008" (±0.019mm)	±0.0012" (±0.030mm)	******
Density	2.2g/cc			Helium Pycnometer
Temperature range	-25°C~ 125°C			******
Phase Change Softening Temperature	50°C ~ 60°C			******
Thermal Conductivity	0.95W/mK			ASTM D5470 (modified)
Thermal Impedance @ 50 psi(345 KPa)	0.024℃-in²/W 0.15℃-cm²/W	0.053℃-in²/W 0.34℃-cm²/W	0.080℃-in²/W 0.52℃-cm²/W	ASTM D5470 (modified)

Standard Thicknesses:

0.005"(0.127mm) 0.008"(0.203mm) 0.010"(0.254mm)

Consult the factory alternate thickness.

Standard Sizes:

10" x 16"(254mm x 406mm) 16" X 400' (406mm X 121.92M)

TIC™800 series are supplied with a white release paper and a bottom liner. TIC800™ series is available in kiss cut an extended pull tab liner or individual die cut shapes.

Peressure Sensitive Adhesive:

Peressure Sensitive Adhesive is not applicable for TIC™800 series products.

Reinforcement:

No reinforcement is necessary.

加拿大Canada
TEL: +001-604-2998559
E-mail: frances@ziitek.com.tw
Http://www.thermazig.com

台湾Taiwan
TEL: +886-2-22771007
E-mail: frances@ziitek.com.tw
Http://www.ziitek.com.tw

东莞Dongguan
TEL: +86-769-38801208
E-mail: frances@ziitek.com.tw
Http://www.ziitek.com.cn

昆山Kunshan
TEL: +86-512-57816297
E-mail: kelvin@ziitek.com
Http://www.ziitek.com.cn

杭州Hangzhou
TEL: +86-571-63850366
E-mail: alex@ziitek.com
Http://www.ziitek.com.cn

长沙Changsha
TEL: +86-731-86949836
E-mail: jor@ziitek.com
Http://www.ziitek.com.cn

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